

N-Channel Enhancement Mode Power MOSFET

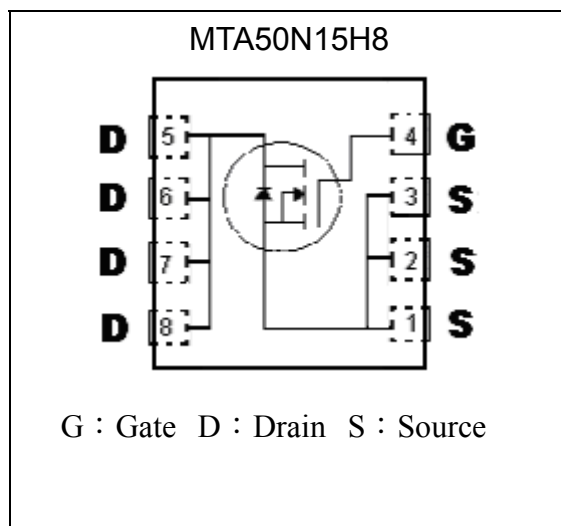
MTA50N15H8

Features

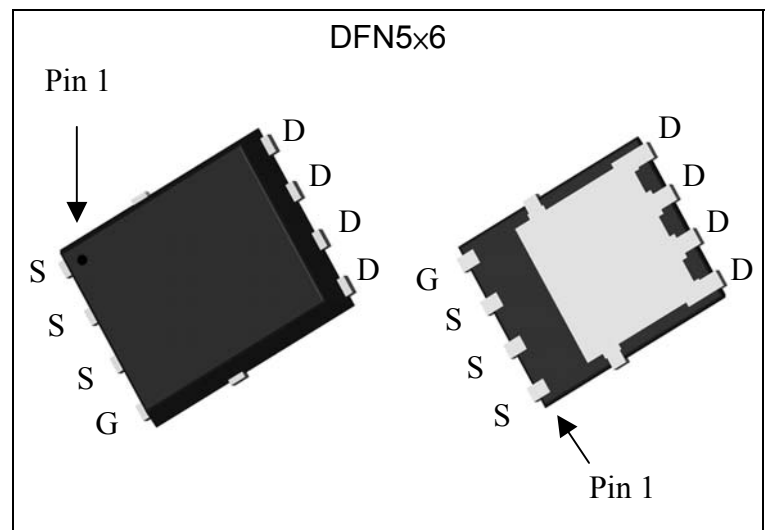
- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- Pb-free lead plating and Halogen-free package

BV_{DSS}	150V
I_D@V_{GS}=10V, T_C=25°C	26A
I_D@V_{GS}=10V, T_C=100°C	18.4A
I_D@V_{GS}=10V, T_A=25°C	4.6A
I_D@V_{GS}=10V, T_A=70°C	3.7A
R_{DS(ON)}@V_{GS}=10V, I_D=20A	44mΩ (typ)
R_{DS(ON)}@V_{GS}=4.5V, I_D=10A	43mΩ (typ)

Symbol

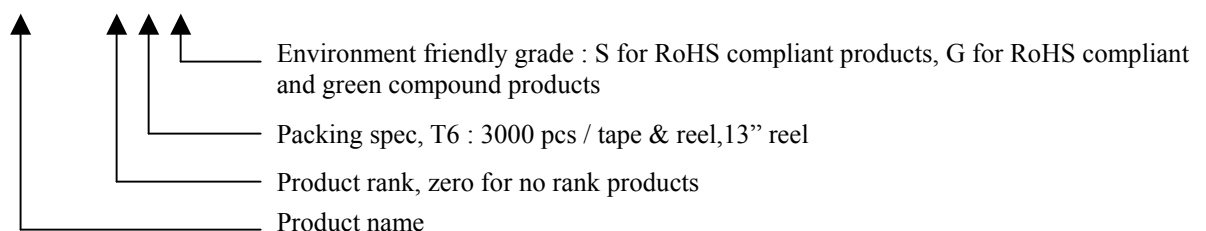


Outline



Ordering Information

Device	Package	Shipping
MTA50N15H8-0-T6-G	DFN 5 ×6 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel



**Absolute Maximum Ratings** ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	150	V
Gate-Source Voltage		V _{GS}	±20	
Continuous Drain Current @T _C =25°C, V _{GS} =10V		I _D	26	A
Continuous Drain Current @T _C =100°C, V _{GS} =10V			18.4	
Continuous Drain Current @T _A =25°C, V _{GS} =10V		I _{DSM}	4.6	
Continuous Drain Current @T _A =70°C, V _{GS} =10V			3.7	
Pulsed Drain Current		I _{DM}	104	
Avalanche Current @ L=0.1mH		I _{AS}	20	
Single Pulse Avalanche Energy @ L=1mH, I _D =10Amps, V _{DD} =50V		E _{AS}	50	mJ
Power Dissipation	T _C =25°C	P _D	93	W
	T _C =100°C		46.5	
	T _A =25°C	P _{DSM}	2.5	
	T _A =70°C		1.6	
Operating Junction and Storage Temperature		T _j , T _{stg}	-55~+175	°C

*Drain current limited by maximum junction temperature

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{\theta JC}$	1.6	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-ambient, max (Note 4)	$R_{\theta JA}$	50	

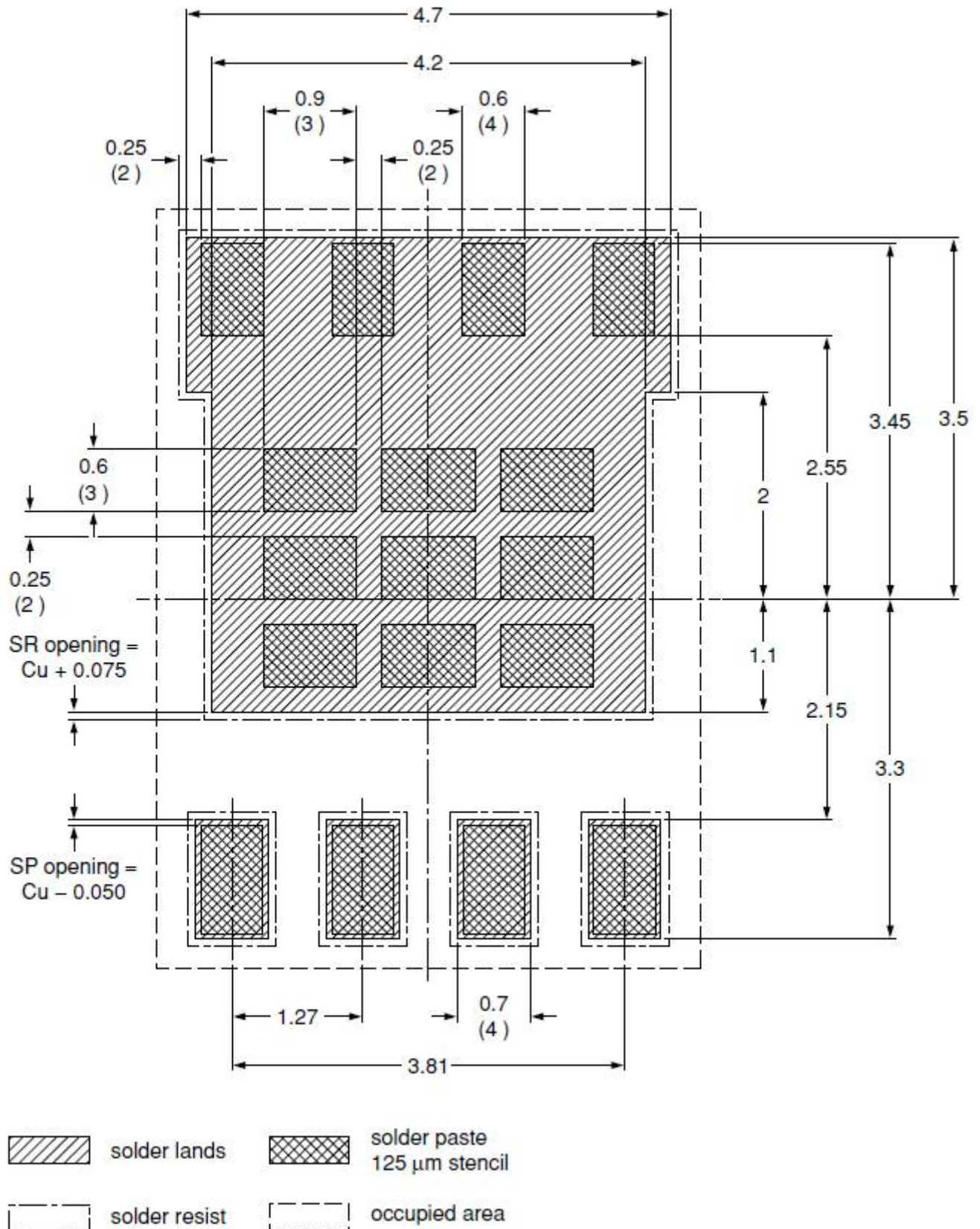
- Note : 1. The power dissipation P_D is based on $T_{J(MAX)}=175^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.
3. Ratings are based on low frequency and low duty cycles to keep initial $T_J=25^{\circ}\text{C}$.
4. When mounted on 1 in² copper pad of FR-4 board, $t \leq 10\text{s}$; 125°C/W when mounted on minimum copper pad.
5. 100% tested by conditions of $L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $I_{AS}=5\text{A}$, $V_{DD}=25\text{V}$.

**Characteristics (Tj=25°C, unless otherwise specified)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	150	-	-	V	V _{GS} =0V, I _D =250μA
ΔBV _{DSS} /ΔT _j	-	0.1	-	V/°C	Reference to 25°C, I _D =250μA
V _{GS(th)}	0.5	-	1.2	V	V _{DS} = V _{GS} , I _D =250μA
*G _{FS}	-	31	-	S	V _{DS} =10V, I _D =4.6A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V
I _{DSS}	-	-	1	μA	V _{DS} =120V, V _{GS} =0V
	-	-	25		V _{DS} =120V, V _{GS} =0V, T _j =125°C
*R _{DS(ON)}	-	44	58	mΩ	V _{GS} =10V, I _D =20A
	-	43	60		V _{GS} =4.5V, I _D =10A
Dynamic					
*Q _g	-	63.5	95	nC	V _{DS} =75V, I _D =4.6A, V _{GS} =10V
*Q _{gs}	-	3.5	-		
*Q _{gd}	-	9.8	-		
*t _{d(ON)}	-	11.4	23	ns	V _{DS} =75V, I _D =4.6A, V _{GS} =10V, R _G =6Ω
*t _r	-	20.4	40		
*t _{d(OFF)}	-	100.6	200		
*t _f	-	22.2	44		
C _{iss}	-	2105	3160	pF	V _{GS} =0V, V _{DS} =30V, f=1MHz
C _{oss}	-	144	216		
C _{rss}	-	63	95		
R _g	-	1.6	-	Ω	f=1MHz
Source-Drain Diode					
*I _S	-	-	26	A	
*I _{SM}	-	-	104		
*V _{SD}	-	0.8	1.2	V	I _S =20A, V _{GS} =0V
*t _{rr}	-	37	-	ns	V _{GS} =0V, I _F =4.6A, dI _F /dt=100A/μs
*Q _{rr}	-	58	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

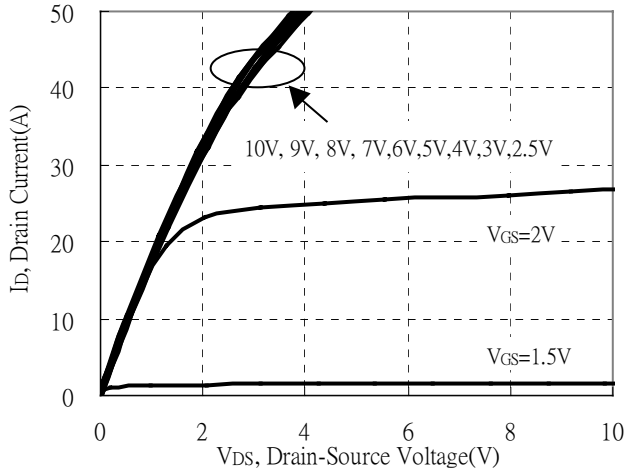
Recommended Soldering Footprint & Stencil Design



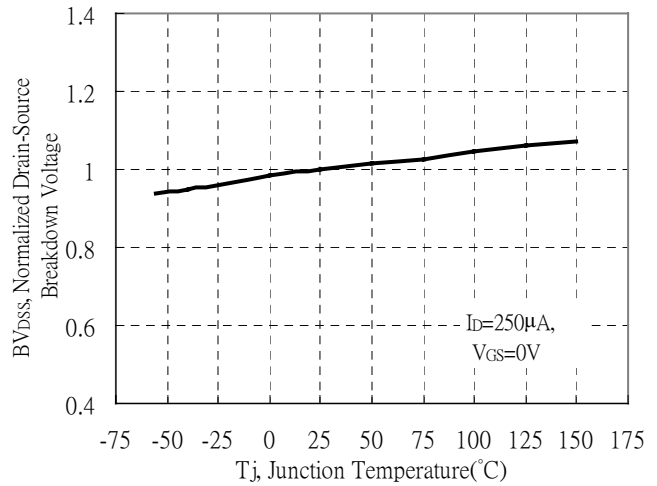
unit : mm

Typical Characteristics

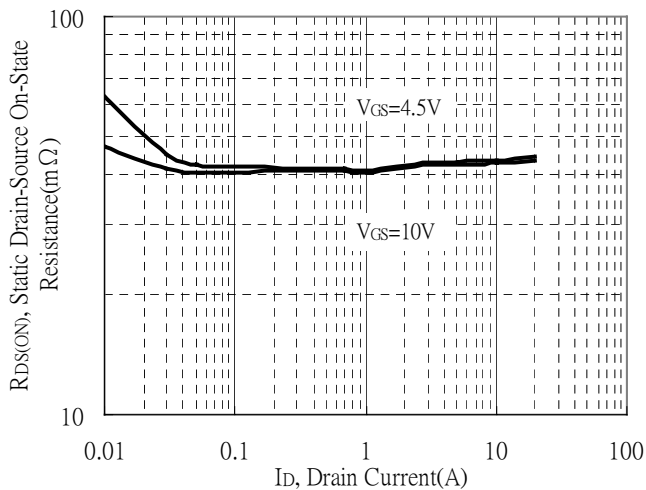
Typical Output Characteristics



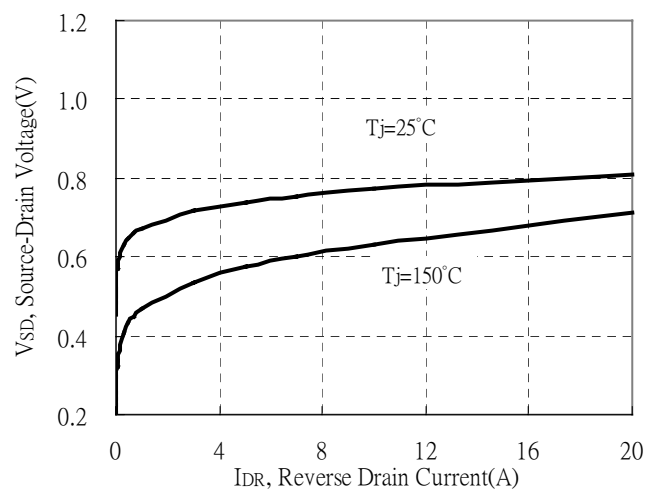
Brekdown Voltage vs Ambient Temperature



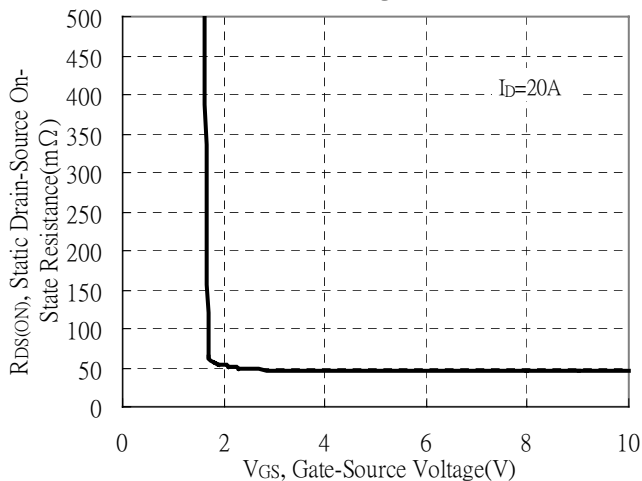
Static Drain-Source On-State resistance vs Drain Current



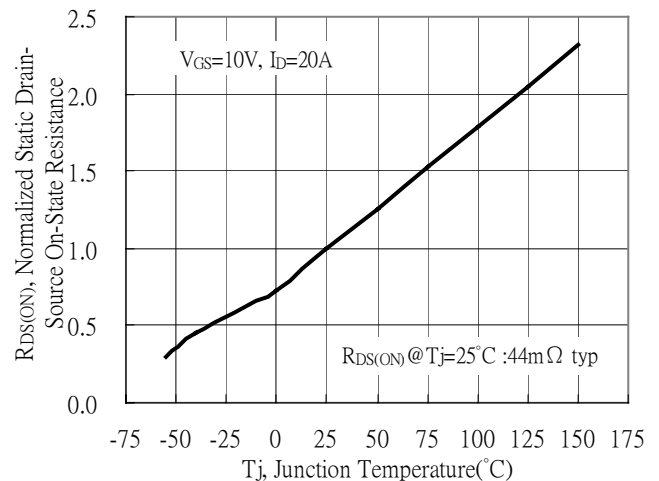
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

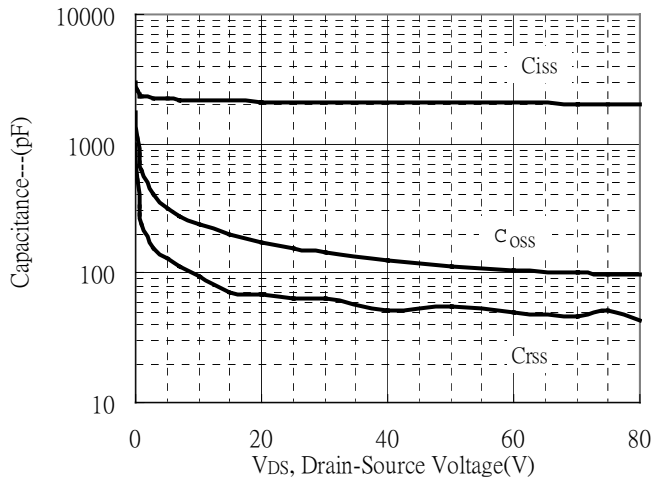


Drain-Source On-State Resistance vs Junction Temperature

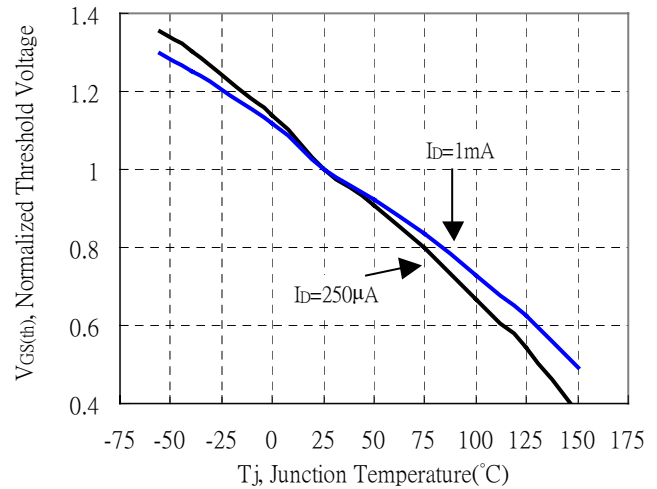


Typical Characteristics(Cont.)

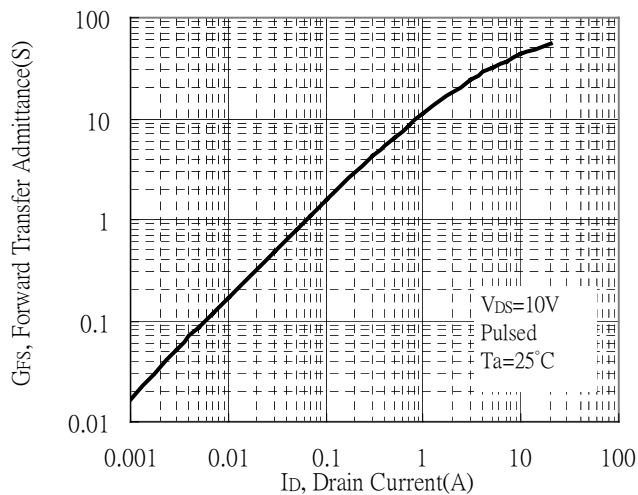
Capacitance vs Drain-to-Source Voltage



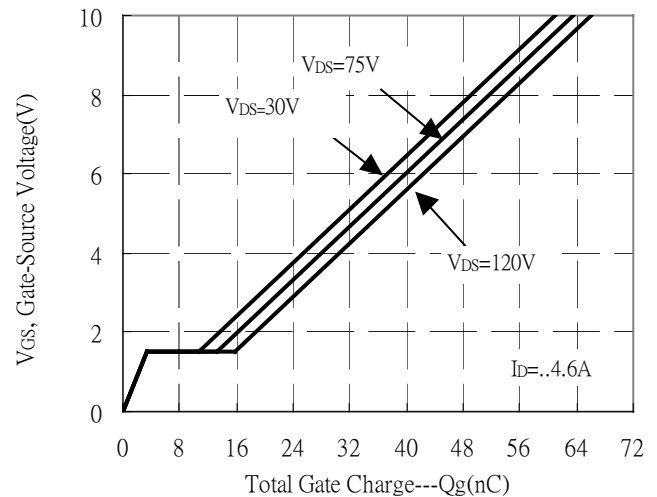
Normalized Threshold Voltage vs Junction Temperature



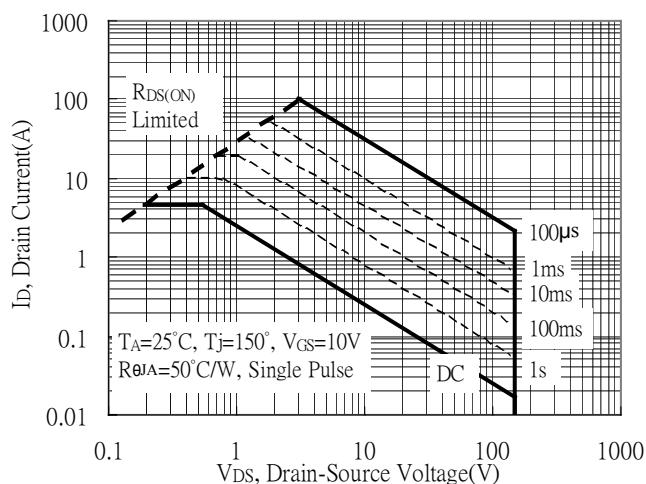
Forward Transfer Admittance vs Drain Current



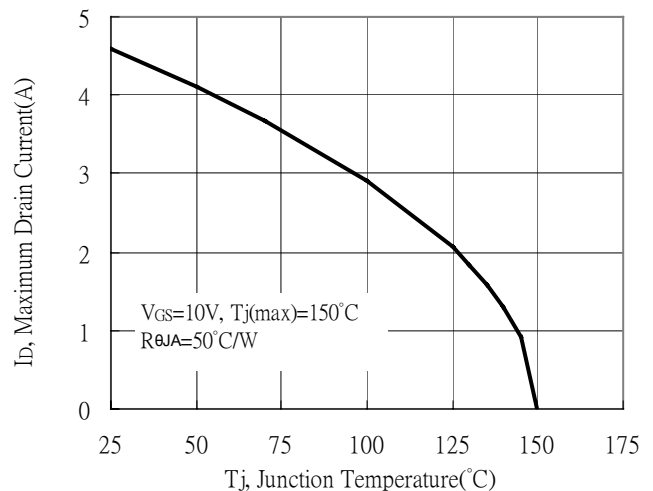
Gate Charge Characteristics



Maximum Safe Operating Area

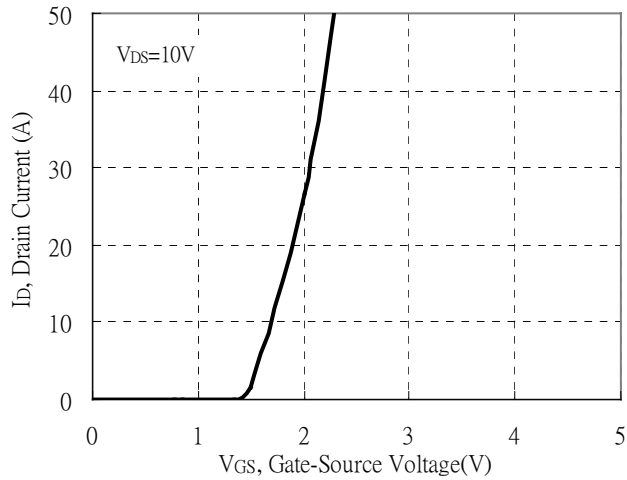


Maximum Drain Current vs Junction Temperature

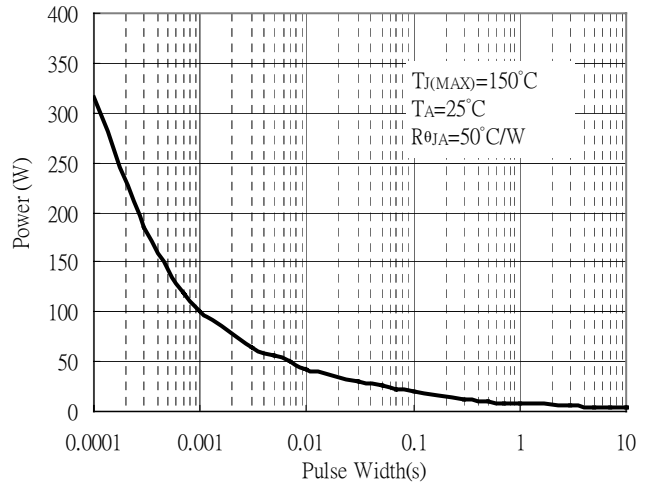


Typical Characteristics(Cont.)

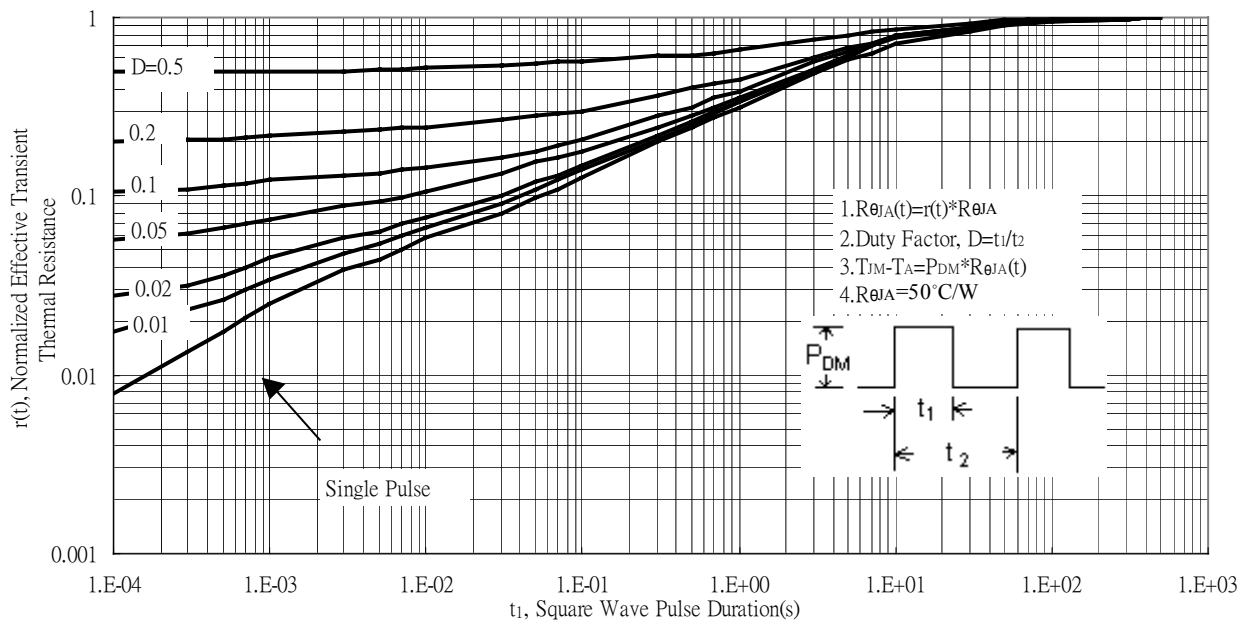
Typical Transfer Characteristics



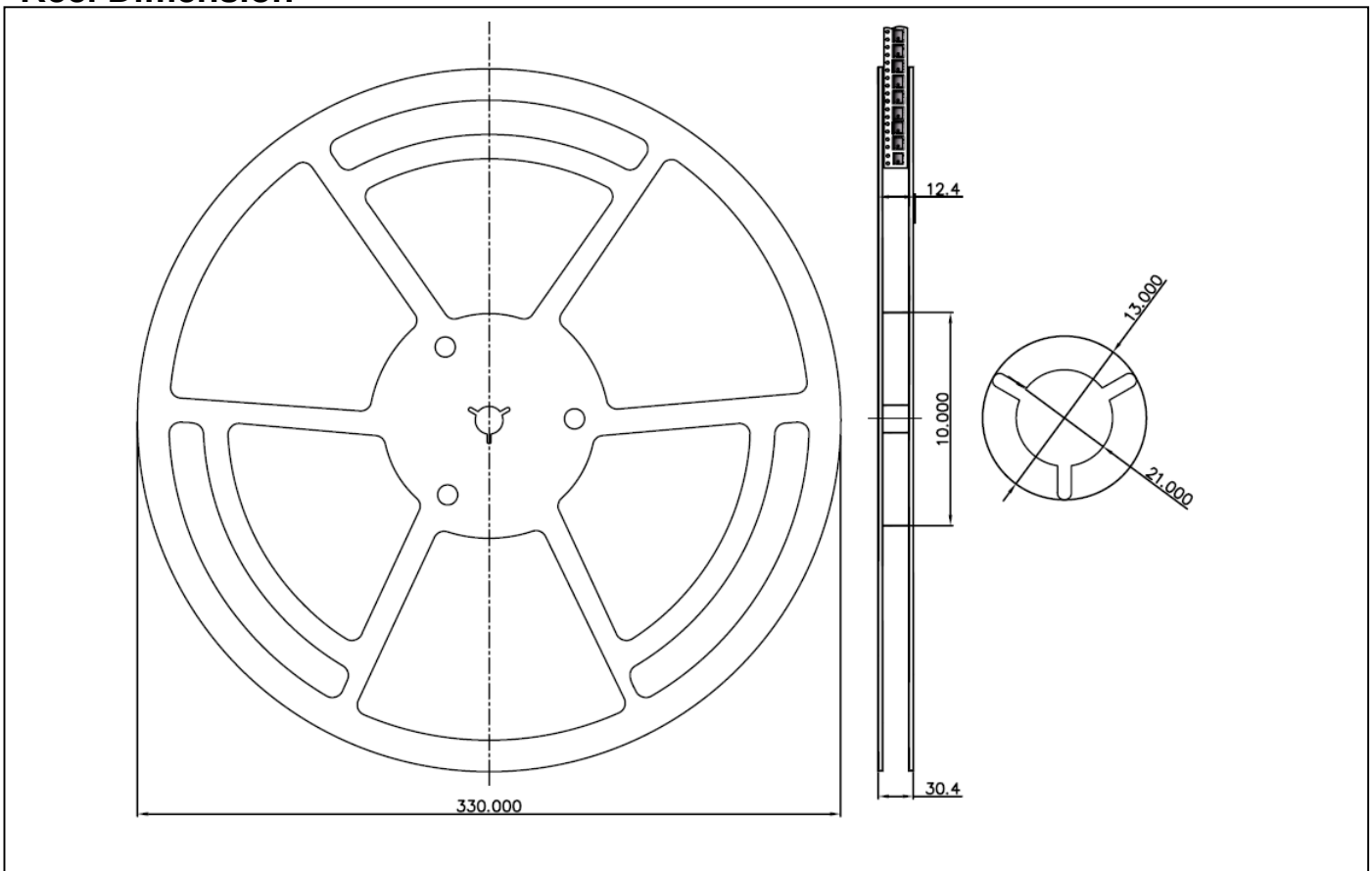
Single Pulse Maximum Power Dissipation



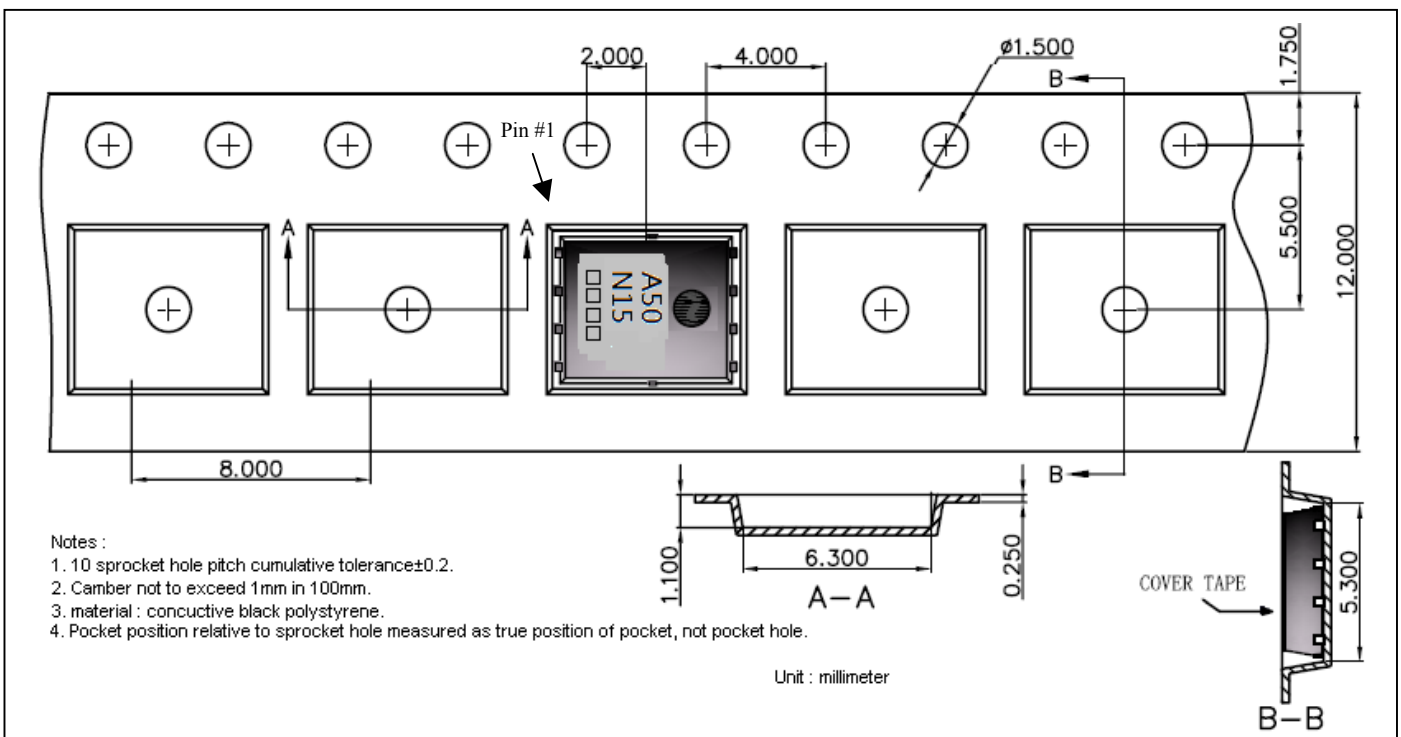
Transient Thermal Response Curves



Reel Dimension



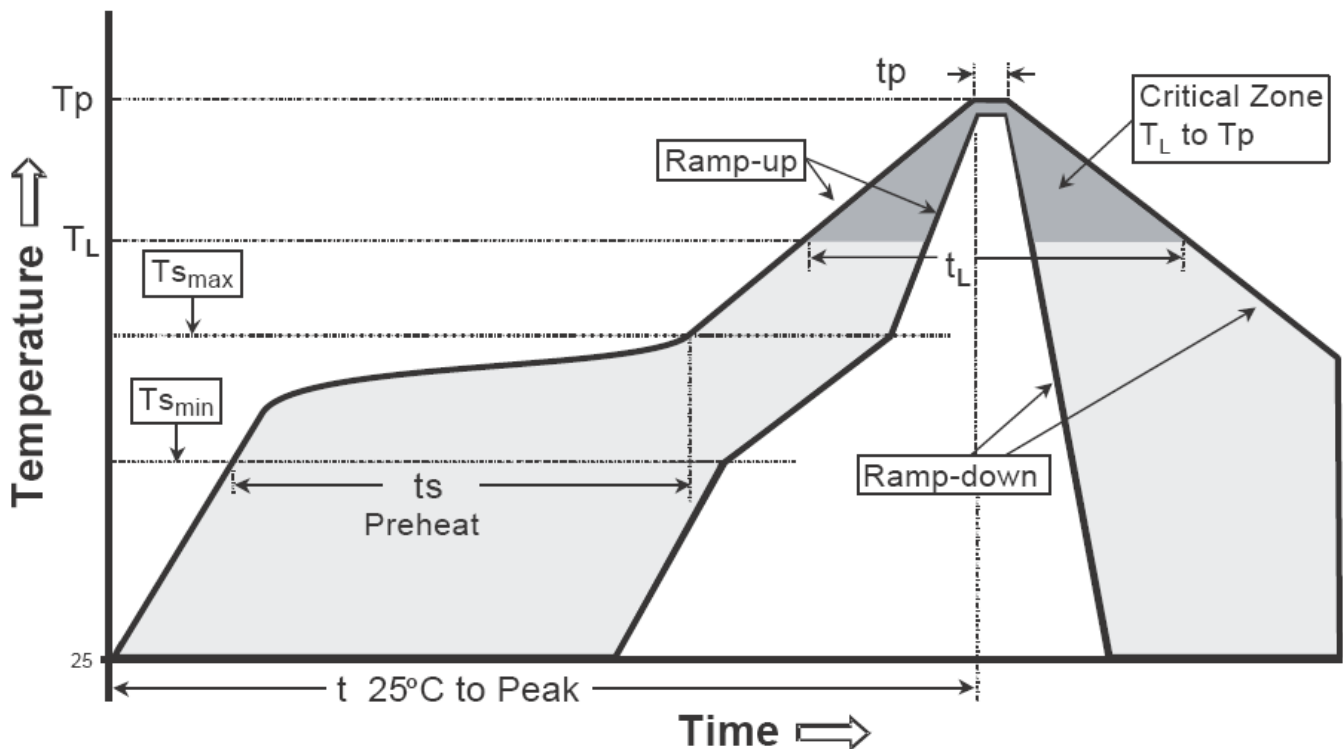
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

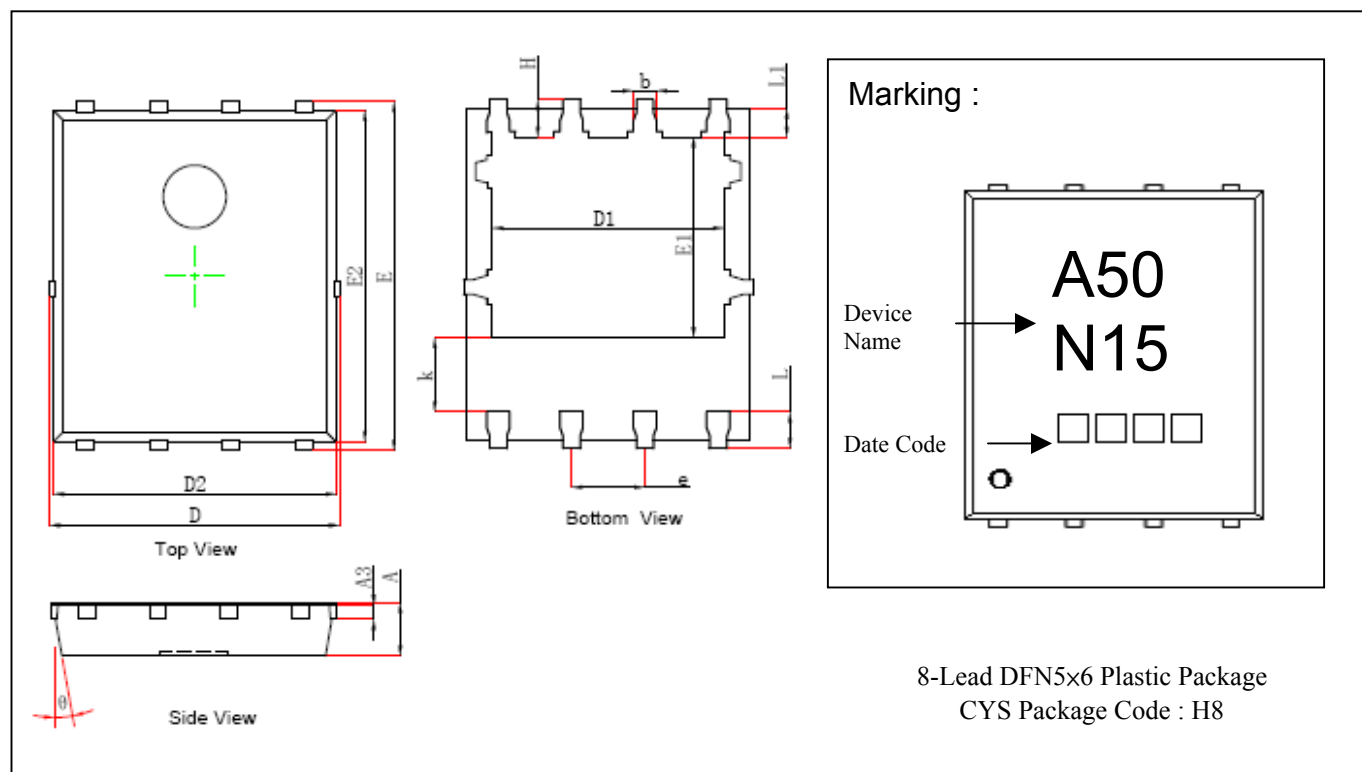
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T_{smax} to T_p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T_{smin})	100°C	150°C
-Temperature Max(T_{smax})	150°C	200°C
-Time(t_{smin} to t_{smax})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T_L)	183°C	217°C
- Time (t_L)	60-150 seconds	60-150 seconds
Peak Temperature(T_p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t_p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

DFN5x6 Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039	k	1.190	1.390	0.047	0.055
A3	0.254	REF	0.010	REF	b	0.350	0.450	0.014	0.018
D	4.944	5.096	0.195	0.201	e	1.270	TYP.	0.050	TYP.
E	5.974	6.126	0.235	0.241	L	0.559	0.711	0.022	0.028
D1	3.910	4.110	0.154	0.162	L1	0.424	0.576	0.017	0.023
E1	3.375	3.575	0.133	0.141	H	0.574	0.726	0.023	0.029
D2	4.824	4.976	0.190	0.196	θ	10°	12°	10°	12°
E2	5.674	5.826	0.223	0.229					

Notes: 1. Controlling dimension: millimeters.

2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.